

Abstract

A different materials bonded member includes a ceramic base material and a metallic member which are bonded together through an Au solder material. The solder material is disposed on a bonding surface of the ceramic base through a given active metal layer or a given metalized layer and the solder material is heated and melted to form a pre-coat layer adhering to the bonding surface, the metallic member is disposed on a surface of the pre-coat layer through a barrier layer having a given function. A bonded part is formed by solidifying the pre-coat layer after it has been heated and melted under given temperature conditions to bond the ceramic base and the metallic member to one another.